MicroCoat Potting & Encapsulation

Potting and encapsulation compounds are formulated to provide intimate contact with the encapsulated media and at the same time provide properties such as high dielectric strength, shock resistance and thermal conductivity. MicroCoat Technologies full line of encapsulation compounds offer many options. Please call us if you do not see what you want.

Product	Polymer Type	Cure Temp. °C	Mix Ratio A:B	Pot Life/Gel Time >	Shore Hardness	Application Notes
E53101	Two Part Epoxy Potting Compound	RT	1:01	11 min.	82D	The workhorse of the industry. Its low viscosity, mix ratio, and rapid gel time allow for use with both **manual and automatic equipment**. Vol. Res= 5.9x1014 ohm-cm
E53102	Two Part Epoxy	3 hr. at 150°C	7.2:1	3 hr. at RT.	88D	Excellent thermal conductivity potting compound and adhesive. High Tg for use in **severe heat, chemical and environmental conditions**.
E53103	Two Part Epoxy	RT	40:13.7	185 min.	90D	An excellent **room temperature cure** , thermally conductive potting and encapsulation compound.
E53104	Two Part Epoxy	RT	1:01	25 min.	75D	Clear doming or Decoupage epoxy. Excellent for use **over wood and metals.**
E53105	Two Part Epoxy	RT	40:09.3	90 min.	90D	**Heat transfer epoxy** filled with special shapes and sizes of aluminum which have been computer designed to maximize heat transfer.
U55360-1	High Performance Two Part Urethane	RT	100:20:00	6 min.	60A	Low viscosity potting and encapsulating polyurethane. It is used in potting **electrical devices for automotive and telecommunication**.
U55335	Hight Performance Two Part Urethane	RT	100:27:00	20 min.	35A	A flexible low durometer hardness, urethane potting and encapsulating compound. Also ideal for **mold making**.
U55380	Hight Performance Two Part Urethane	RT	100:26:00	11 min.	80A	Urethane casting and encapsulation compound modified for **resistance to harsh environments and moisture**. Has a low mixed viscosity and will fill most intricate parts void free.
E53201	Two Part Heat Cure Encapsulation	100	100:50:00	30 min.	90D	Excellent product for encapsulation of **high voltage coils under thermal and mechanical shock**.
E53202	Two Part Heat Cure Encapsulation	100	100:44:00	30 min.	86D	Combination of low viscosity and excellent thermal shock tolerance makes this product good for **"Under Hood" applications**.
E5-3202-03	Two Part Heat Cure Encapsulation	100	1:01	30 min.	86D	Unfilled, lover viscosity version of E53202. Customer can cast over **large bore aggregate filler** or use unfilled.